

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF THE CLAIMS

What is claimed is:

Claims 1-29 (canceled)

30. (currently amended) A fan out type package structure, comprising:
- ~~an isolating~~a base without a die receptor cavity formed therein;
 - a die adhered ~~to said isolating~~on said base;
 - a first dielectric layer formed on said ~~isolating~~ base and ~~filled~~filling in a space except said die on said ~~isolating~~ base;
 - a second dielectric layer formed on said first dielectric layer and said die, wherein said second dielectric layer includes an opening~~and said second dielectric layer having first openings on first pads of said die;~~
 - a ~~first~~ contact conductive layer formed on said ~~first openings~~pads of said die and within said opening to electrically ~~coupling~~couple with said first pads, respectively;
 - a ~~first~~ conductive lines formed on said second dielectric layer and ~~corresponding~~ said first contact conductive layer substantially filling said opening, and said ~~first~~ conductive lines being extended out from corresponding said ~~first~~ contact conductive layer to corresponding first end points, wherein said corresponding first end points are inside a surface of said second dielectric layer;
 - a ~~first~~an isolation layer formed on said ~~first~~ conductive lines and said second dielectric layer, ~~and said first isolation layer having second openings on said first conductive lines; and~~
 - solder balls passing through said isolation layer and welded on said second openings and ~~electrical coupling with said first conductive lines for coupling with said conductive lines,~~ respectively.

31. (original) The package structure in claim 30, wherein surfaces of said first dielectric

layer and said first die are at same level.

Claims 32-35 (canceled)

36. (previously presented) The package structure in claim 30, wherein materials of said first dielectric layer and said second dielectric layer comprise UV curing type material, heat curing type material, or the combination thereof.

37. (currently amended) The package structure in claim 30, wherein said first—contact conductive layer comprises Ti, Cu, and the combination thereof.

38. (currently amended) The package structure in claim 30, wherein said first—conductive lines comprise Ni, Cu, Au, and the combination thereof.

39. (currently amended) The package structure in claim 30, wherein a material of said ~~isolating~~—base is glass, silicon, ceramic, or crystal material.

40. (currently amended) The package structure in claim 30, further comprising an epoxy layer formed on a back surface of the base.

41. (original) The package structure in claim 30, wherein said isolation layer comprises epoxy, resin, and the combination thereof.

Claims 42-47 (canceled)

48. (new) The package structure in claim 30, wherein said die is a sawed die and adhered on said base by a picking and placing system.